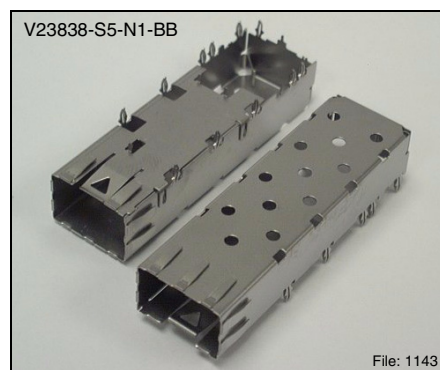
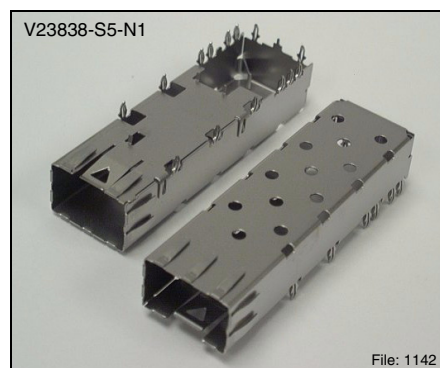


Press-fit Cage for Small Form-factor Pluggable (SFP) Transceiver

V23838-S5-N1
V23838-S5-N1-BB

Features

- 3D foot design for improved press-fit retention and contact to host board holes
- One-piece, stainless steel construction
- Low emission design via fold-back spring fingers – no openings for radiation to pass through
- Enhanced transceiver kick-out springs
- Simple and fast installation/removal
- Host board holes not damaged when cage is removed
- Heat transfer windows on all SFP cage surfaces
- Supports MSA compliant host board layouts and transceiver designs



Part Number	Description
V23838-S5-N1	For single-sided mounting
V23838-S5-N1-BB	For double-sided "belly to belly" mounting (see Figure 3)

Description

Infineon is offering its cage for Small Form-factor Pluggable (SFP) transceivers with one of the most rigid mechanical designs available on the market. The cage is designed for press fit applications in order to reduce high volume manufacturing effort. Externally bent bezel contact springs and one-piece construction enhance EMI performance.

Application Notes

- Testing of rear connector may take place before SFP Cage is installed onto host board
- SFP cage mounting holes should be plated with HASL, gold, or immersion silver finish per MSA dimensional recommendations
- For double-sided mounting, host board thickness is .118 in [3.0 mm] minimum per the MSA. For belly-to-belly applications, three mounting feet are removed to avoid interference (V23838-S5-N1-BB)
- Supports any single sided, belly to belly, or offset belly to belly configuration with a minimum pitch of 16.25 mm
- Installation of the SFP cage should be done with a solid metal block across the top surface of the cage. Block dimensions to be controlled by customer
- Removal of the cage should be done with an internal solid metal block
- The Infineon SFP cage does not cause any damage when carefully removed; the outside profile of the 3D feet is smooth and will not destroy pre-plated host board mounting holes
- Trapped fluids from washing process must be dried to prevent corrosion beneath the SFP cage
- Cage retention depends on finished hole size and plating thickness

SFP Cage Host Board Mechanical Layout

SFP Cage Host Board Mechanical Layout

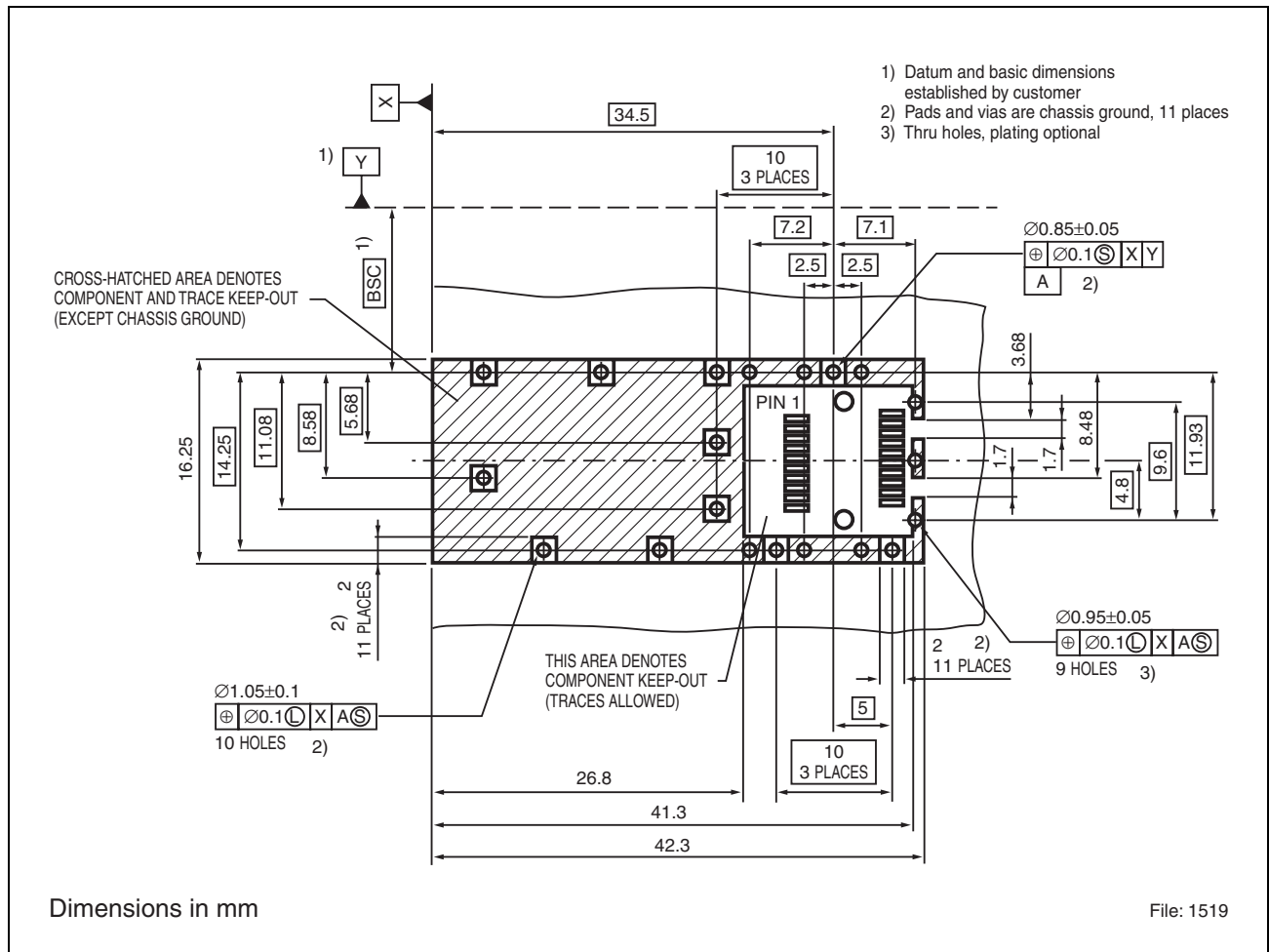


Figure 1 Single-sided Host Board Layout

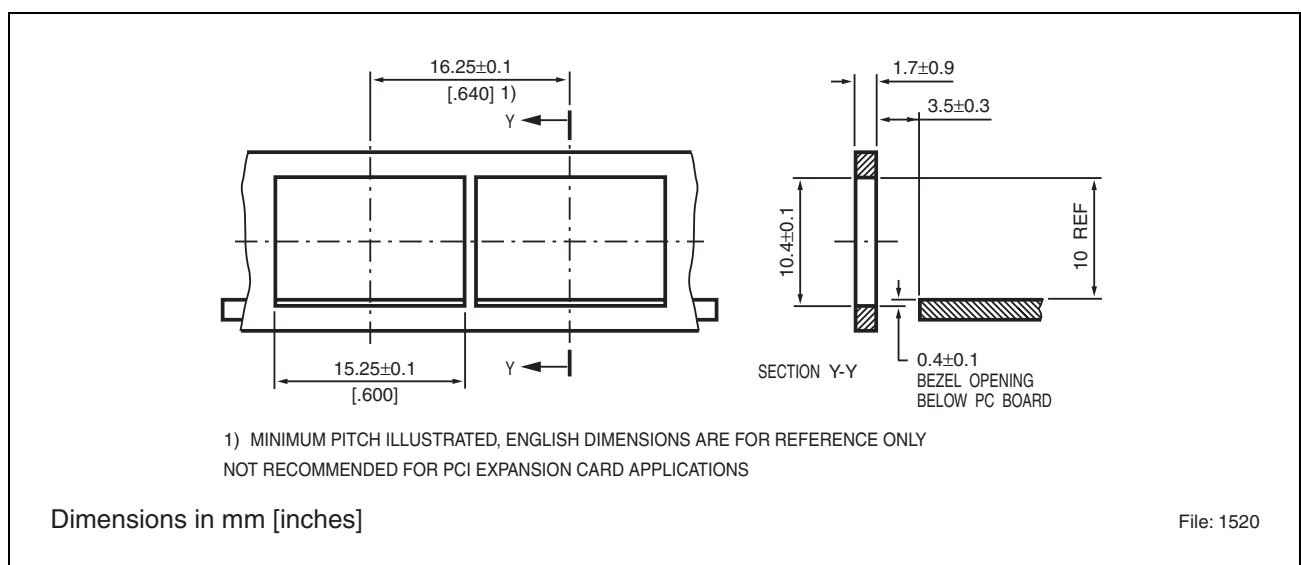


Figure 2 Recommended Bezel Design

SFP Cage Host Board Mechanical Layout

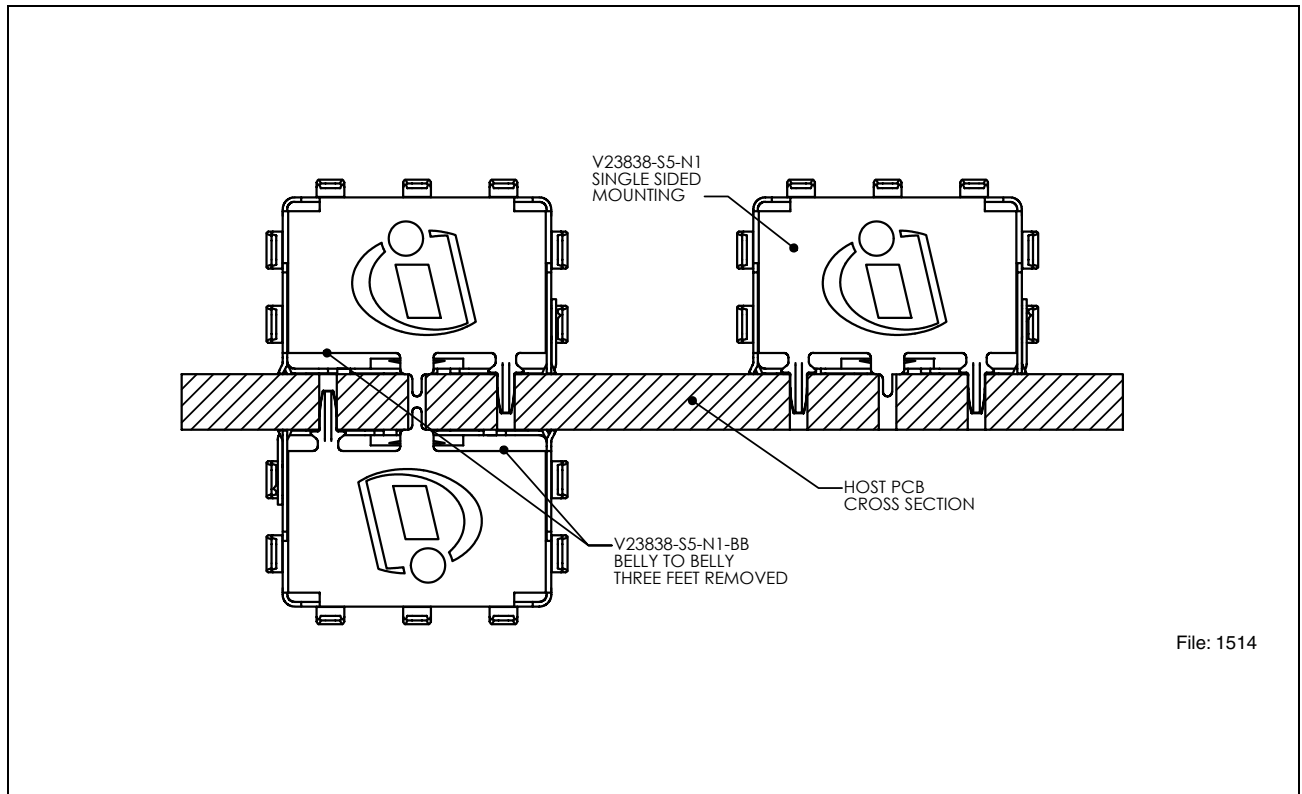
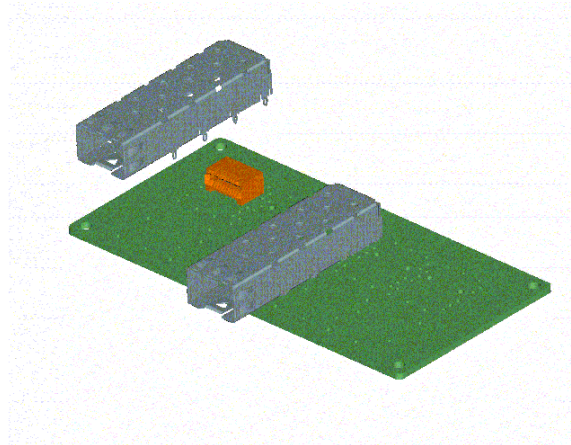


Figure 3

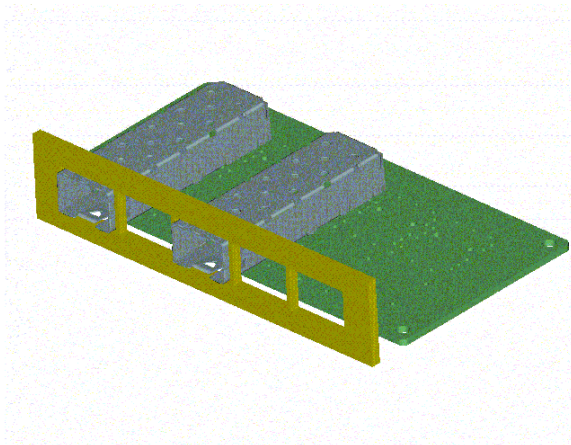
SFP Cage Host Board Mechanical Layout

Single-sided Application



File: 1515

Figure 4

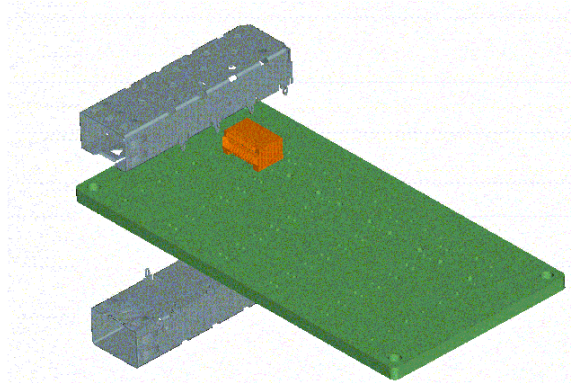


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Figure 5

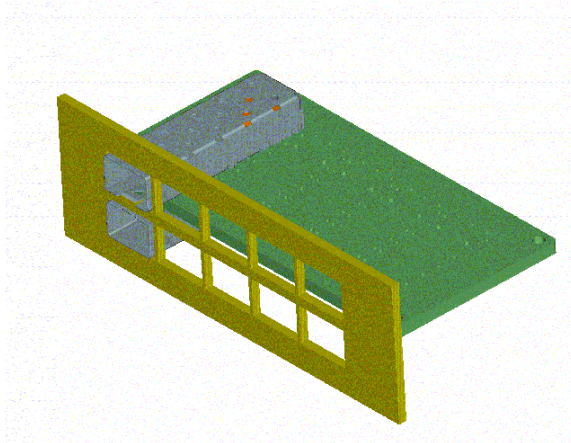
SFP Cage Host Board Mechanical Layout

Belly to Belly Application



File: 1517

Figure 6



File: 1518

Figure 7

Package Outlines

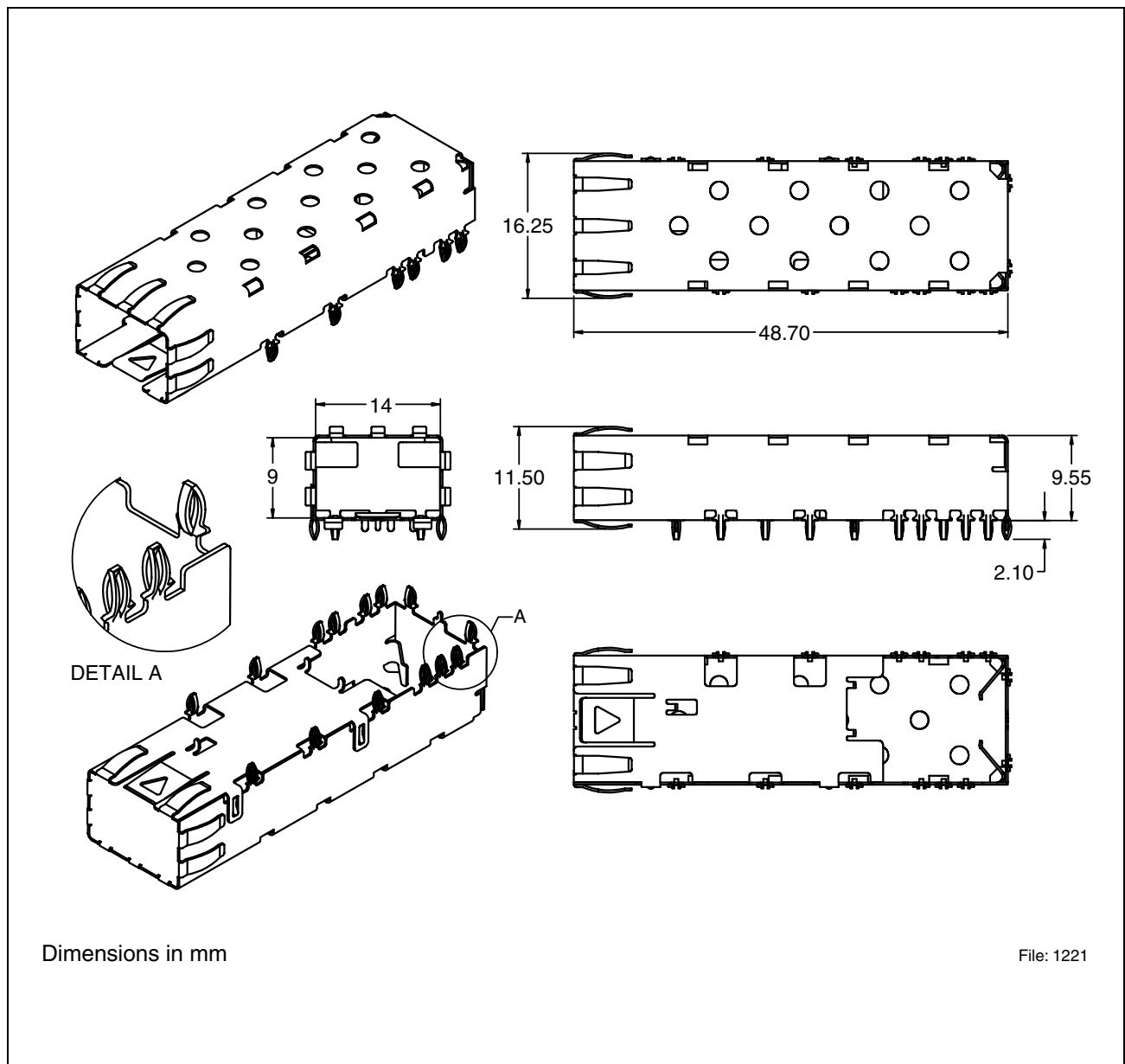


Figure 8 V23838-S5-N1

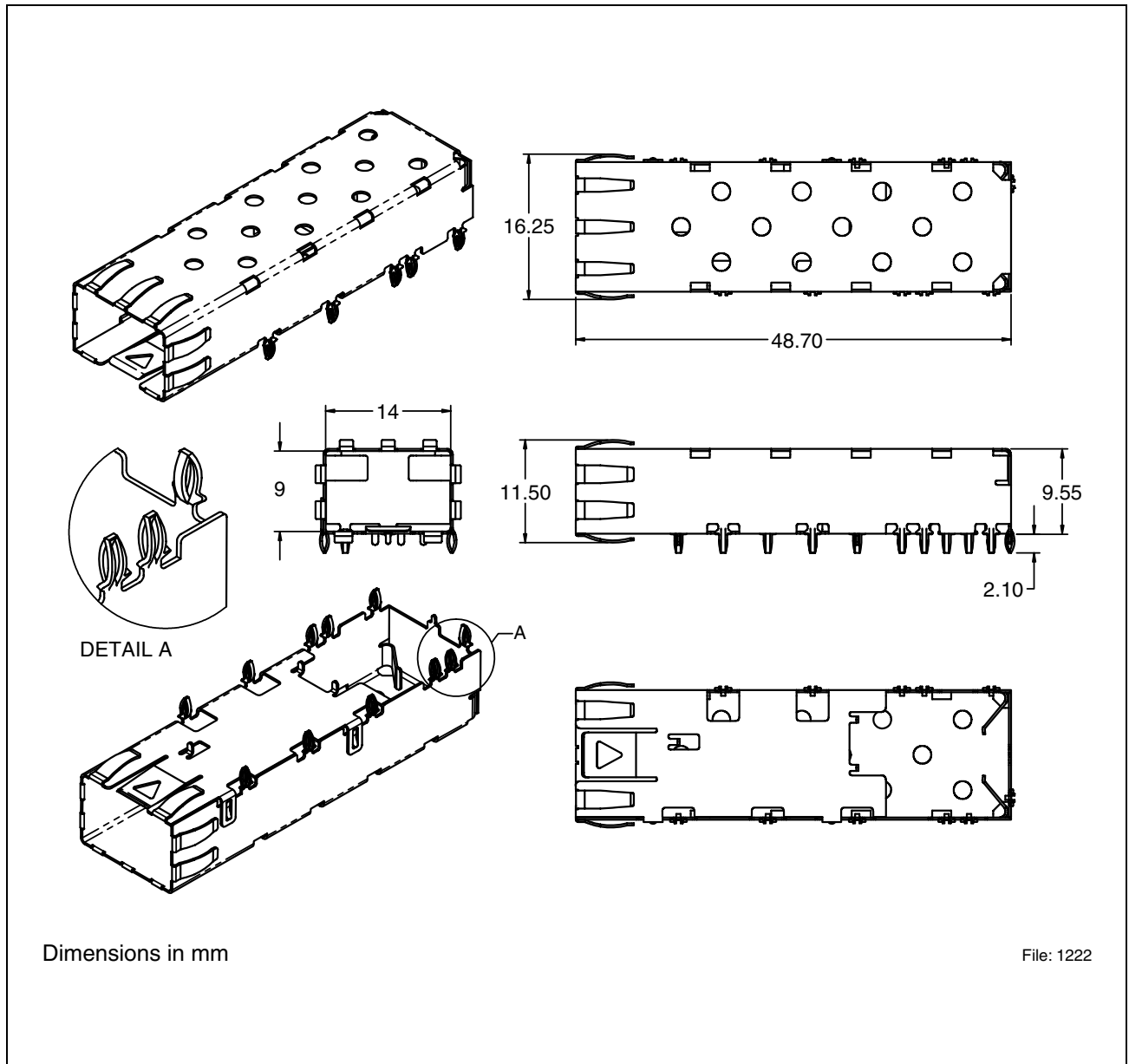


Figure 9 V23838-S5-N1-BB

V23838-S5-N1
V23838-S5-N1-BB

Revision History: **2003-08-07** DS3

Previous Version: 2003-07-08

Page	Subjects (major changes since last revision)
1	“Preliminary Data” removed

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